Photo IC Panasonic

## PNA4S54F

## Photodiode with amplifier functions

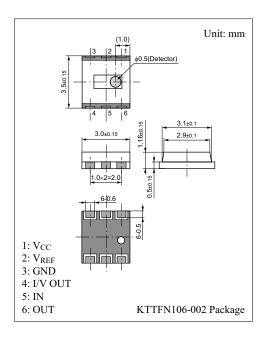
#### For optical control systems

#### ■ Features

- Small package, × 52 speed
- Reflow soldering possible

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Operating supply voltage	V <sub>CC</sub>	6	V	
Power dissipation	$P_{\mathrm{D}}$	250	mW	
Operating ambient temperature	T <sub>opr</sub>	-20 to +70	°C	
Storage temperature	T <sub>stg</sub>	-40 to +85	°C	



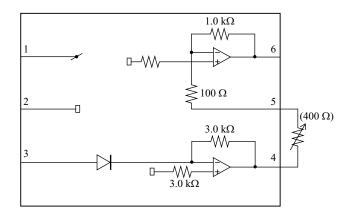
#### ■ Electrical Characteristics $T_a = 25$ °C±3°C, $V_{CC} = 5.0$ V, $V_{REF} = 2.5$ V, $R_L = 10$ k $\Omega$ , $C_L = 10$ pF, $V_R = 200$ $\Omega$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Operating supply voltage *4	V <sub>CC</sub>		4.5	5.0	5.5	V
Output voltage *1	V <sub>O</sub>	$PI = 50 \mu W, \lambda = 780 \text{ nm}$	-95	-140	-190	mV
Output offset voltage *2	V <sub>OFF</sub>		-10	0	10	mV
Output maximum voltage	V <sub>OM</sub>	V <sub>REF</sub> standard	-2.0	-2.2	_	V
Reference voltage *4	V <sub>REF</sub>		2.0	2.5	2.75	V
Supply current	I <sub>CC</sub>	No signal condition	_	1.5	20	mA
Cutoff frequency *3	$f_{C(-3dB)}$	Gurantee item on design	_	80	_	MHz
Rise time	t <sub>r</sub>	$V_{\rm O} = 1 \text{ V}, 10\% \text{ to } 90\%$		5		ns
Fall time	$t_{\rm f}$					

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. \*1: Standard voltage level;  $V_{REF}$  (Exclude output offset voltage)
    - \*2: Standard voltage level;  $V_{\text{REF}}$
    - \*3:  $20 \log (V_O (f_C MHz)/V_O (1 MHz)) = -3$
    - \*4:  $(V_{CC} V_{REF})$  Voltage: more than 2.0 V

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### ■ Block Diagram



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